IMAPS-UK Professional Development Course

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Professional Development Course

Wafer and Package Dicing Technology

20-25 May 2021

Highlights:

- *Wafer and Package Dicing*
- *Blade Dicing*
- *Laser Dicing*
- *Latest Dicing Technologies*
- *Dicing Solutions*
- *Troubleshooting*
- *Practical Tips*
- *Reference Material*

Sawing is the first and most critical step in the die processing operation. There are many variables involved in sawing process such as wafer thickness, the width of the saw streets, the metal composition of the wafer, and the die size. Factors such as blade speed, cutting patterns, or even the electrical charge carried by the DI water used can have a significant impact on the yield of the sawn dice. The wafer dicing process yield is optimised through the proper selection of the dicing blade. Failure to perform the process correctly can cause mechanical damage to the die.

The objective of this course is to introduce engineers and technicians to the basic principles and options of the various dicing methods and its functions. This course will expose the participants to the various dicing technology such as blade dicing, laser dicing and stealth dicing for both wafer and package technology. In this 4 half-day online webinar, the issues and problem solving for the various defect types and causes will be addressed. The highlights of this workshop are the case studies as well as the video presentations of the different dicing processes. It is important to understand how these techniques work to enable participants to gain a good understanding, practical experience, and continuous-improvement knowledge to be well equipped to champion the dicing process in their organisation.

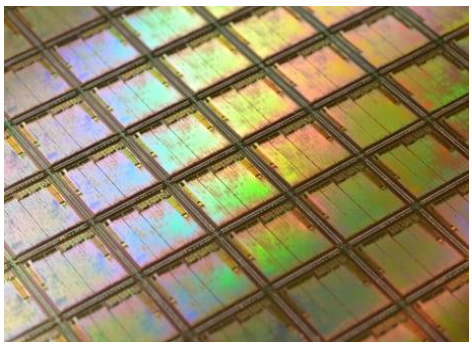
Registration:

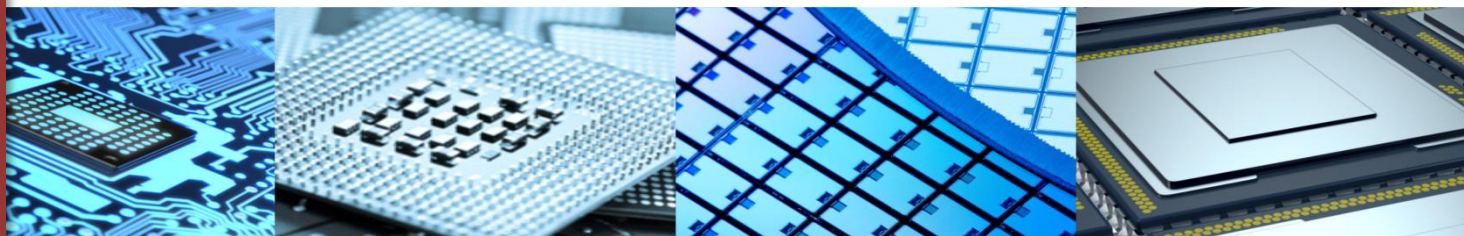
	Delegates
IMAPS Member	*450*
Non Member	*650*
IMAPS Student	*300*

Prices - £ exclude VAT

"Where the Electronics Packaging Industry Meets Online"

Register Here





Course Agenda:

Day 1: Thursday 20 May 2021

Session 1: Introduction to Dicing

Session 2: Dicing Technology Overview

Day 2: Friday 21 May 2021

Session 3: Blade Dicing

Session 4: Dicing Solutions

Day 3: Monday 24 May 2021

Session 5: Laser Dicing

Session 6: New Technologies

Day 4: Tuesday 25 May 2021

Session 7: Issues and Problem Solving

Session 8: Recap, Review and Summary

Each Day will commence at 13:00 and finish at 17:00 (UK time)

Register Here

For further details, please contact IMAPS-UK.

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Who should attend:

- Wafer Dicing Engineers and Technicians
- Package Dicing Engineers and Technicians
- Process Engineers
- FEA Engineers
- Materials Engineers
- Quality Control Engineers
- Reliability Engineers
- Managers

Access to Course Presentations:

Attendance at the Course includes downloadable access to the presentations including audio and visuals.

Your Course Tutor:

Andy Longford, PandA Europe

Andy Longford is founder and managing Partner of technical consulting company PandA Europe, set in 1998 to support microelectronic packaging and assembly. He has been working in the Semiconductor Packaging and Assembly industry for over 30 years, involved in package design, development and assembly projects including LED, MEMS and Power devices, for applications in Automotive, industrial and Consumer products, as well as Aerospace and Defence related products. He has authored over 30 technical papers on Electronics Interconnect, Chip Packaging and Lead-Free electronics developments, with 15 technical articles published and numerous presentations made at conferences worldwide. He has served on a number of UK Government technical committees, he is an EPSRC College peer review member, a registered EU Research Project evaluator, a committee member of IMAPS-UK and a member of the SEMI Europe Advanced Packaging Committee.